



[Total Service provider for Telecommunication Market]

himico Solutions, Inc.

About US



【Company name】 himico Solutions, Inc.

【Address】 Shinbashi Ocean Bld.7F 4-31-3 Shinbashi,
Minato-ku, Tokyo, 150-0004 Japan

【Executive】 Yoshitaka Kodama, Hiroyuki Akaba

【Capital money】 JPY 3,000,000

【Business Field】

Telecommunications (Wireless /Mobile/Network)

【Business contents】

- 1) Original Wireless Module Product Business
- 2) IP/SoC/OEM Products marketing & Sales
- 3) Total Support for R&D/Production
- 4) Japan Entry/Driven Support

【Admission Group】 Bluetooth SIG & WiMedia



- In 1999, himico Project had started to introduce Wireless Technology Product (IP/SoC/Module/Board/Software,etc.) which Semiconductor Distributor and Hardware/Software System Design Company had developed so as to promote Wireless Technology in Japan.
- In 2002, it made an announcement the result of himico Project (Chip,Board,System,etc.) in "Bluetooth EXPO". And also it was continuing to actively promote Wireless Technology through making API Spec Plan, technical seminar and writing the article on technical magazine. The result of the promotion, himico Project was to get good reputation on world wide wireless market.
- ~2003, Each company which developed the product related Wireless Technology got good opportunity of each business chance. himico Project was closed to achieve their purpose.
- In 2004, Preparation "Corporate Company"
- In 2005, it has established " himico Solutions, Inc."



Business Description

<p>Original Wireless Module Business</p>	<p>Standard Bluetooth SPP Module Product (a base in WML-C46/C40 which is made by Mitsumi Electric) and Custom Bluetooth Module Product which based on the required specification of the Customer. And plan to release New Wireless Module.</p>
<p>IP/SoC/Chip Sales Support</p>	<p>It supports a Domestic and International Technology Product in the sales and Technical support from Design-in until Business Close.</p>
<p>Total Engineering Support for R&D/Production</p>	<p>It supports Total Engineering Support (general, planning, the architect, the design, the evaluation, consulting and so on,) until Mass Production.</p>
<p>Japan Entry Program of Overseas Vendor</p>	<p>It implements the program to entry the Technology Product of the overseas vender into the Japanese market.</p>

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Bluetooth ブルートゥース・ワイヤレス製品

Ver2.0 対応高速シリアル通信モジュール

■製品概要

ミクシ電機製の最新 Bluetooth モジュール (*1) を採用し、内蔵 FLASH ROM にスタック・SPP(*2) プロファイルを実装したコンパクト型高速シリアル通信モジュールです。アンテナ有りの標準型モジュールですから、そのまま機器への組み込みが可能です。高周波の無線や RF/アンテナのチューニング等は一切必要ありません。少数ロットの製品向けにコネクタ付きモジュールもございます。また、シリアル通信と同時に双方向の音声通話可能なトランシーバー機能を標準搭載していますので、「データ+音声 (Voice/Audio)」の対応アプリケーションに活用可能です。UART は高速シリアル (物理速度設定最大 960Kbps) に対応しているため、大容量のデータを送るアプリケーション (画像伝送等 *3) にも適しています。

(*1) UML-C43A/U43A-R - Bluetooth Ver.2.0+EDR 対応 (*2) SPP は Serial Protocol Profile の略 (*3) 2000ドット/4800dpi 対応



■特徴

- ・モジュール独自の AT コマンド仕様で Bluetooth 簡単接続
- ・Master/Slave 各種設定情報は FLASH ROM に自動保存 (再設定不要)
- ・マクロ機能搭載 (電源投入時に自動実行を行う製品 PnP 機能)
- ・AFH 機能で他の無線機器との干渉を最大限防止
- ・eSDC 採用で、高音質かつ省切りの無い双方向音声通話 (Voice/Audio) を実現
- ・低消費電力対応 (15mW 等の低消費電力モードを自動制御)
- ・480Kbps 級の高速データ通信

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■対応アプリケーション

RS232C 等のシリアル AFE 実装する機器全般	
ビジネス	ハンディターミナル、バーコードリーダー、ハンディプリンター、ラベルプリンター、バーコードプリンター、キーボード、計測器、測定器、CCD監視カメラ
FA/物流	
医療	血液検査などの各種ヘルスケア機器
音声系	ヘッドホン、コードレスホン、トランシーバー、機内放送、アラーム受信



■製品仕様

	Class1 HIM-C43A	Class2 HIM-C46A
規格 Profile	GAP, SDAP, SPP(Dev-A/B)	
電源電圧	3.3V(3.2~3.4V)	2.8~3.4V
送信電力		-82dBm Typ.
出力レベル	20dBm max	+4dBm max
動作温度範囲	-40~+70°C	-40~+85°C
外形寸法	13.2(W)x24.8(L)x2.05(H)mm	11.8(W)x17.6(L)x2.5(H)mm
EMI 規格	FCC, CE	

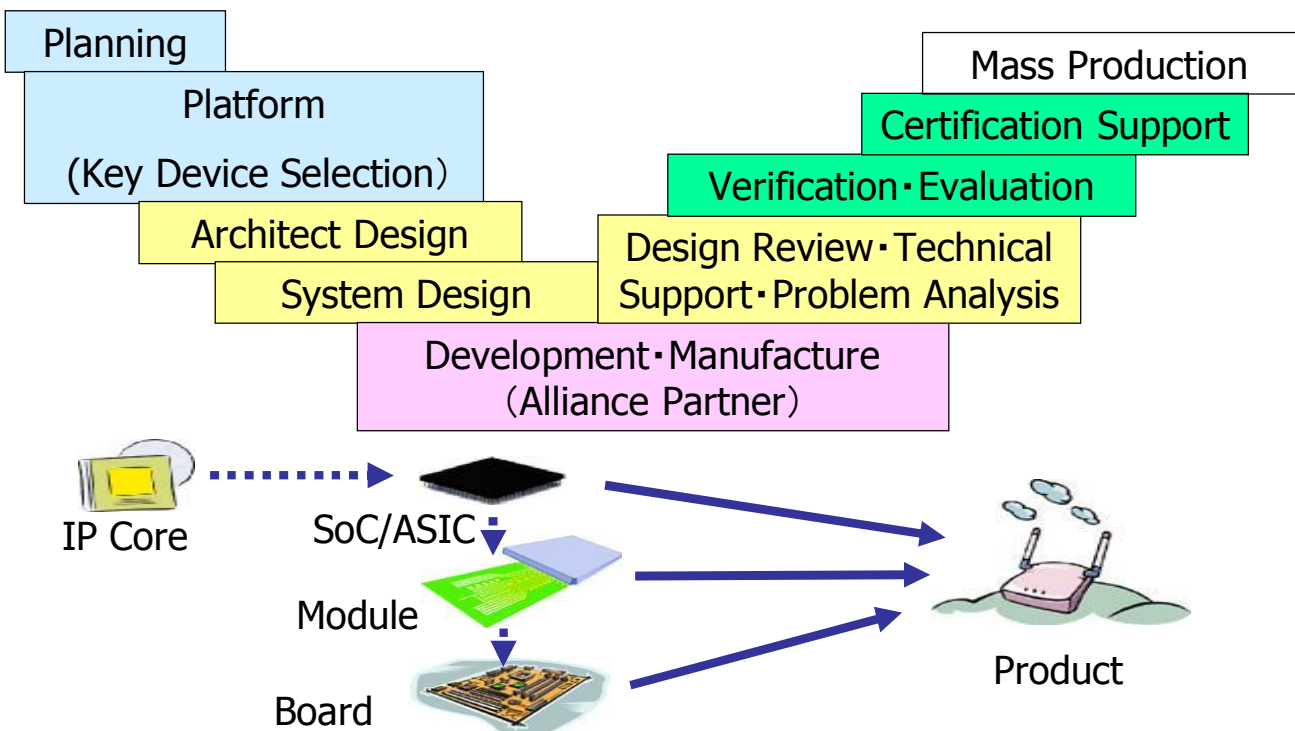
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2007年7月現在

IP	Domestic A Company	【LVDS】 High Speed Sub-LVDS Remarkable Product supported to the 3G Cellar Phone
	Overseas B Company	【Next Generation Wireless】 Advanced Wireless Baseband/MAC Technology Product supported to the Wireless USB、Multimedia-UWB an so on.
	Overseas C Company	【Analog AFE】 Video、Portable AV、 Wireless Technology Product supported to Digital Consumer Device.
SoC	Overseas D Company	The Chip and Module supported to the Power Line Communications (PLC)



It supports the overseas vendor which wants to enter a Japanese market.

【Basic Business Plan for 6 Month】

- ① **Market Research** (The similar product, the technology, the marketability & target application and so on)
↓
- ② **Product Marketing to Priority Customer** (The inquiry of demonstration & evaluation, needs and so on)
↓
- ③ **Promotion & Sales Activity** by WEB, News, Exhibition, Private Seminar and so on.
↓
- ④ **Product Marketability** (Feedback information into the vendor)
↓
- ⑤ **Matching to the Semiconductor Distributor** (Sales Agreement)

Note) ※The above is the example of the chip business of SoC/ASIC and so on.

Management Team



★Yoshitaka Kodama(CEO)

He was a Director in Cosmic.
 He engaged for Research and Development on the field of Communication System Firmware / Software IP/End Product more than 20 year.
 Especially, he engaged in lot of Mass Production designs such as UNIX, Analog modem, ISDN TA-G3 FAX machine and acquired high skill as the Communication Technology person.
 After that, it aims at the Mobile Communication, and It had he was success to make New Soft Modem of PDC/PHS/CDMA as middleware and it was a license to the domestic and international major Communication company. (No.1 sales as the middleware).
 He is supporting the product for the most advanced technology Bluetooth/WiFi at present and so on.
 He holds the member of " MCPC " which is Mobile and Wireless trade association and so on.
 He makes Mobile, Wireless and Network a specialized field.
 He is temporary chairman of formerly himico project.
 He has the book of " the Bluetooth & PAN application building guide " of October of Ohm Co. Computer & Network LAN (the joint work).



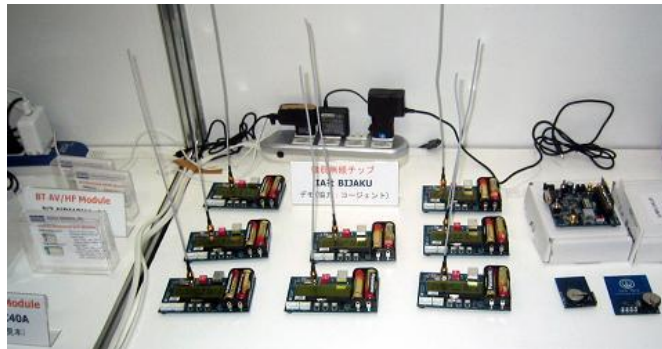
★Hiroyuki Akaba(CFO)

He was Synopsys Senior Account Manager for 5 years in Synopsys before joining himico Solution Inc.
 He engages in the marketing and the sale activity of the overseas semiconductor and IP Core vendor more than 20 years.
 He introduced SCSI I/F LSI product to major Computer and Peripheral company in Japan, being the first time.
 It grows and it fixed a SCSI market in Japan as the standard interface.
 Also, he engaged in the popularization in IEEE1394 and the fiber channel, too.
 Besides, he has more experience of the ASIC product, the RAID product, the Network product and the PC chip set, too.
 He had many design win in major System company. After that, he engages in the license business of the IP Core product (USB, PCI, the Ethernet, the others).
 He had a sales to major Semiconductor company and System company. Also, he had many design win in all major company.
 He is a best field of creating the start-up of the new business having the Marketing and Sales Strategy.

Target · Possession Technology



Wireless	Bluetooth、WiFi、ZigBee WUSB/UWB、WiMAX
Mobile	PHS(PIAFS)、 CDMA(EVDO)、W-CDMA (FOMA/VGS)
Cable	PLC(Powerline)
Network	Based TCP/IP、SIP/VoIP、 DNLA(uPnP)
Interface	Sub-LVDS、Serial ATA、 PCI_Express



Product Support Success Story

- R & D
 - Bluetooth Camera
 - Bluetooth Handy Printer
 - Bluetooth PAN Access Point
 - Bluetooth BIP for Cellular Phone
 - Bluetooth A/V Speaker, etc
- Proto Type
 - Bluetooth Telephony System
 - Bluetooth Modem/ISDN TA, etc
- Mass production Support
 - Bluetooth Adapter for PDC/CDMA/EVDO/FOMA
 - Bluetooth Handsfree System
 - Bluetooth Headset, etc

- Semiconductor Vendor
 - A : USB2.0 Host & PHY, USB2.0 OTG (App: Printer, Game)
 - B : USB2.0 Host, Device, USB2.0 PHY (APP : Printer)
 - C : USB1.1,2.0 Device, Gigabit Ethernet (App: OA, Peripheral, Consumer, Communication, PC Server)
 - D : USB1.1 Host, USB2.0 Device (App: Printer)
 - E : USB2.0 Host (App : All in one)
 - F : AMBA Cores (App : ASIC Platform)
- System Vendor
 - A : All USB1.1, USB2.0, PCI, PCI-Express (App: DTV, Consumer, Printer, Peripheral, Mobile)
 - B : USB2.0 Host, USB2.0 Device & PHY, PCI (App : Game)
 - C : USB1.1 Host, USB1.1 Device, USB2.0 Device, Ethernet, PCI, PCI Express (App: All in one, Printer)
 - D : USB1.1 Host, USB2.0 Device, Ethernet (App : All in one)
 - E : USB2.0 Host, Device & PHY (App: All in one)
 - F : USB2.0 OTG, SDMMC (App : Digital Camera)

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